L Number	Hits	Search Text	DB	Time stamp
1	956	grinding near4 sanding	USPAT;	2004/04/22 11:21
			US-PGPUB	
2	2112	(strandboard or waferboard or chipboard or fiberboard or particleboard	USPAT;	2004/04/22 11:05
		or osb or ((strand or particle or wafer or fiber or chip or wafer) adj1 board)).ti,ab.	US-PGPUB	
3	3	(grinding near4 sanding) and ((strandboard or waferboard or chipboard	USPAT;	2004/04/22 11:04
		or fiberboard or particleboard or osb or ((strand or particle or wafer or fiber or chip or wafer) adj1 board)).ti,ab.)	US-PGPUB	
4	8	(strandboard or waferboard or chipboard or fiberboard or particleboard	USPAT;	2004/04/22 11:07
		or osb or ((strand or particle or wafer or fiber or chip or wafer) adj1 board)) same (grinding near4 sanding)	US-PGPUB	
5	7	((strandboard or waferboard or chipboard or fiberboard or particleboard	USPAT;	2004/04/22 11:07
		or osb or ((strand or particle or wafer or fiber or chip or wafer) adj1	US-PGPUB	
		board)) same (grinding near4 sanding)) not ((grinding near4 sanding)		
		and ((strandboard or waferboard or chipboard or fiberboard or		
	: 	particleboard or osb or ((strand or particle or wafer or fiber or chip or wafer) adj1 board)).ti,ab.))		
6	14	thickness with (grinding near4 sanding)	USPAT; US-PGPUB	2004/04/22 11:09
7	2	(strandboard or waferboard or chipboard or fiberboard or particleboard	USPAT;	2004/04/22 11:07
		or osb or ((strand or particle or wafer or fiber or chip or wafer) adjl board)) and (thickness with (grinding near4 sanding))	US-PGPUB	
8	14	thickness with (grinding near4 sanding)	USPAT;	2004/04/22 11:10
			US-PGPUB	
9	51	(wood or wooden or woody) with (grinding near4 sanding)	USPAT;	2004/04/22 11:11
			US-PGPUB	
10	293	grinding near4 sanding	EPO; JPO;	2004/04/22 11:21
			DERWENT	0004/04/00 11 10
11	4	thickness with (grinding near4 sanding)	EPO; JPO;	2004/04/22 11:19
12	31	(wood or wooden or \$7board) with (grinding near4 sanding)	ЕРО; ЈРО;	2004/04/22 11:23
			DERWENT	